

Intelligent Subscriber Line Interface Circuit Am79R240*/Le79R240 Device

APPLICATIONS

- **Optimized for Voice over Broadband and related applications**
 - Cable telephony
 - Integrated Access Devices (IAD)
 - Smart Residential Gateways (SRG)
 - LAN Systems

FEATURES

- **Monitor of two-wire interface voltages and currents supports**
 - Voice transmission
 - Internal chip ring generation
 - Programmable DC feed characteristics
 - Independent of battery
 - Current limited
 - Selectable off-hook and ground-key thresholds
 - Power cross and fault detection
- **Supports internal short loop ringing**
- **+5 V and battery supplies**
- **Dual battery operation for system power saving**
 - Automatic battery switching
- **Compatible with inexpensive protection networks**
 - Accommodates low tolerance fuse resistors or PTC thermistors
- **Metering capable**
 - 12 kHz and 16 kHz
- **Tip-open state supports ground start signaling**
- **5 REN with 15 V DC offset trapezoid.**
 - For US standard:
 - drives ring up to 4.4 kft of 26 gauge wire.
 - or
 - drives ring up to 7 kft of 24 gauge wire.
 - For European (British) standard:
 - drives ring up to 1.7 km of 0.5 mm copper cable.
- **Space Saving Package Options (8x8 QFN)**

RELATED LITERATURE

- **080250 Le79Q2241/2242/2243 QISLAC Data Sheet**
- **080262 Intelligent Access™ Voice Solutions Evaluation Board User's Guide**
- **080344 Le79R2xx/Le79Q224x ISLIC™/Quad ISLIC™ Technical Reference**

ORDERING INFORMATION

An ISLAC™ device must be used with this part.

Device	Package
Am79R240JC*	32-pin PLCC
Le79R240JC	32-pin PLCC
Le79R240QC**	32-pin QFN

*This product can be ordered using ordering part numbers Am79R240 or Le79R240. The Am79R240 ordering part number will be discontinued after 6/30/02, at which time the product will only be available using the Le79R240 ordering part number.

**Due to size constraints, QFN devices are marked by omitting the "Le" prefix. For example, Le79R240QC is marked 79R240QC.

DESCRIPTION

In combination with an ISLAC™ device, the Le79R240 device implements the telephone line interface function. This enables the design of a low cost, high performance, fully software programmable line interface for multiple country applications worldwide. All AC, DC, and signaling parameters are fully programmable via microprocessor or GCI interfaces on the ISLAC device. Additionally, the Le79R240 device has integrated self-test capabilities to resolve faults to the line circuit.

BLOCK DIAGRAM

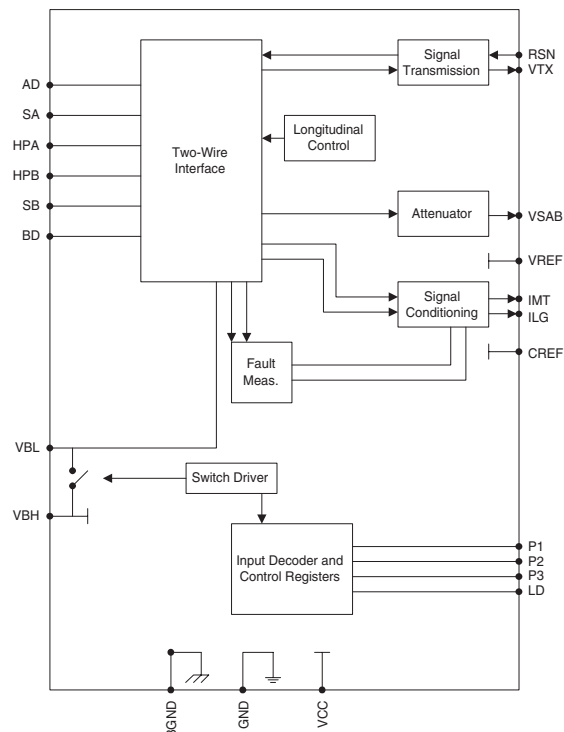


Table of Contents

APPLICATIONS1
FEATURES1
RELATED LITERATURE1
ORDERING INFORMATION1
DESCRIPTION1
BLOCK DIAGRAM1
PRODUCT DESCRIPTION3
LE79R240 DEVICE INTERNAL BLOCK DIAGRAM5
FEATURES OF THE INTELLIGENT ACCESS™ CHIP SET6
CHIP SET BLOCK DIAGRAM - FOUR CHANNEL LINE CARD EXAMPLE6
CONNECTION DIAGRAM7
PIN DESCRIPTIONS8
ABSOLUTE MAXIMUM RATINGS9
THERMAL RESISTANCE9
ELECTRICAL OPERATING RANGES9
SPECIFICATIONS10
POWER DISSIPATION10
DC SPECIFICATIONS11
TRANSMISSION SPECIFICATIONS12
RINGING SPECIFICATIONS12
CURRENT-LIMIT BEHAVIOR12
THERMAL SHUTDOWN FAULT INDICATIONS13
OPERATING MODES13
OPERATING MODE DESCRIPTIONS14
THERMAL-MANAGEMENT EQUATIONS14
TIMING SPECIFICATIONS15
WAVEFORMS16
APPLICATION CIRCUIT17
INTERNAL RINGING17
LINE CARD PARTS LIST18
PHYSICAL DIMENSIONS19
32-PIN PLCC19
32-PIN QFN20
REVISION HISTORY21
REVISION B TO C21
REVISION C TO D21
REVISION D TO E21

PRODUCT DESCRIPTION

The Intelligent Access™ voice chip sets integrate all functions of the subscriber line. Two chip types are used to implement the line card — an Le79R240 device and the Le79Q2241/2242/2243 ISLAC device. These provide the following basic functions:

1. The Le79R240 device: A high voltage, bipolar device that drives the subscriber line, maintains longitudinal balance and senses line conditions.
2. The Le79Q2241/2242/2243 ISLAC device: A low voltage CMOS IC that provides conversion, control and DSP functions for the Le79R240 device.

A complete schematic of a line card using the Intelligent Access voice chip sets for internal ringing is shown in the “Chip set Block Diagram - Four Channel Line card Example” on page 6.

The Le79R240 device uses reliable, bipolar technology to provide the power necessary to drive a wide variety of subscriber lines. It can be programmed by the ISLAC device to operate in eight different modes that control power consumption and signaling. This enables it to have full control over the subscriber loop. The Le79R240 device is designed to be used exclusively with the ISLAC devices. The Le79R240 device requires only +5 V power and the battery supplies for its operation.

The Le79R240 device implements a linear loop-current feeding method.

The ISLAC device contains high-performance circuits that provide A/D and D/A conversion for the voice (codec), DC-feed and supervision signals. The ISLAC device contains a DSP core that handles signaling, DC-feed and supervision for all channels.

The DSP core selectively interfaces with three types of backplanes:

- Standard PCM/MPI
- Standard GCI
- Modified GCI with a single analog line per GCI channel

The Intelligent Access voice chip set provides a complete software configurable solution to the BORSCHT functions as well as complete programmable control over subscriber line DC-feed characteristics, such as current limit and feed resistance. In addition, these chip sets provide system level solutions for the loop supervisory functions and metering. In total, they provide a programmable solution that can satisfy worldwide line card requirements by software configuration.

Software programmed filter coefficients, DC-feed data and supervision data are easily calculated with the WinSLAC™ software. This PC software is provided free of charge, and allows the designer to enter a description of system requirements. WinSLAC then computes the necessary coefficients and plots the predicted system results.

The Le79R240 device includes circuitry to report Tip•Ring voltage and metallic and longitudinal currents to the ISLAC device. These inputs allow the ISLAC device to place several key Le79R240 device performance parameters under software control.

The main functions that can be observed and/or controlled through the ISLAC device backplane interface are:

- DC-feed characteristics
- Ground-key detection
- Off-hook detection
- Metering signal
- Subscriber line voltage and currents
- Ring-trip detection
- Abrupt and smooth battery reversal
- Subscriber line matching
- Ringing generation

To accomplish these functions, the ISLIC device collects the following information and feeds it in analog form to the ISLAC device:

- The metallic (IMT) and longitudinal (ILG) loop currents
- The AC (VTX) and DC (VSAB) loop voltage

The outputs supplied by the ISLAC device to the ISLIC device are then:

- A voltage (VHLi) that provides control for the following high-level ISLIC device outputs:
 - DC loop current
 - Internal ringing signal
 - 12 or 16 kHz metering signal
- A low-level voltage proportional to the voice signal (VOUTi)

The ISLAC device performs the codec and filter functions associated with the four-wire section of the subscriber line circuitry in a digital switch. These functions involve converting an analog voice signal into digital PCM samples and converting digital PCM samples back into an analog signal. During conversion, digital filters are used to band-limit the voice signals.

The user-programmable filters set the receive and transmit gain, perform the transhybrid balancing function, permit adjustment of the two-wire termination impedance and provide frequency attenuation adjustment (equalization) of the receive and transmit paths. Adaptive transhybrid balancing is also included. All programmable digital filter coefficients can be calculated using WinSLAC software and loaded into the ISLAC device registers using the system microprocessor. The PCM codes can be either 16-bit linear twos-complement or 8-bit companded A-law or μ -law.

Besides the codec functions, the Intelligent Access voice chip set provides all the sensing, feedback, and clocking necessary to completely control ISLAC device functions with programmable parameters. System-level parameters under programmable control include active loop current limits, feed resistance, and feed mode voltages.

The ISLAC device supplies complete mode control to the ISLAC device using the control bus (P1-P3) and tri-level load signal (LDi).

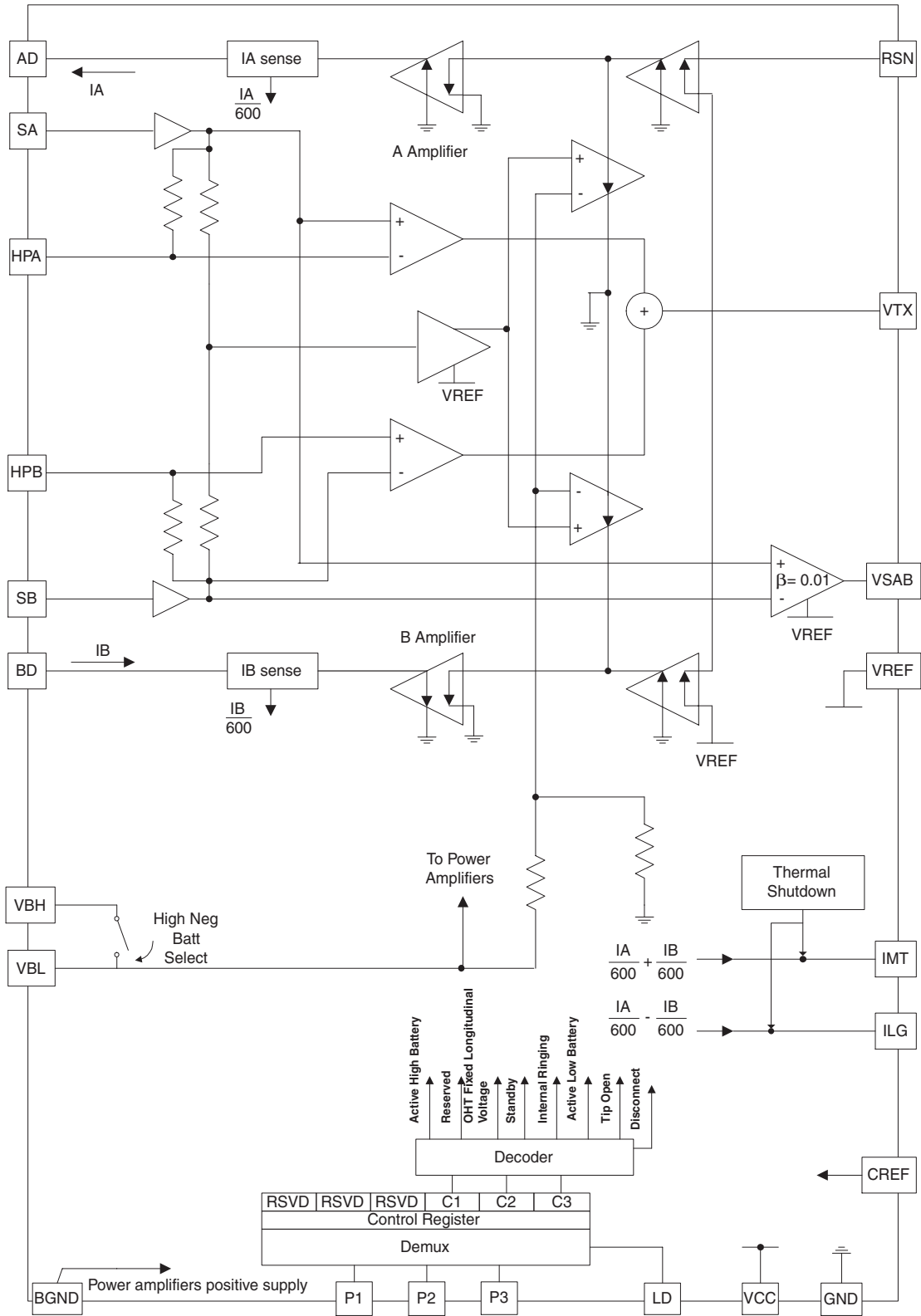
The Intelligent Access voice chip set provides extensive loop supervision capability including off-hook, ring-trip and ground-key detection. Detection thresholds for these functions are programmable. A programmable debounce timer is available that eliminates false detection due to contact bounce.

AC and DC fault detection is also provided.

Note:

i denotes channel number

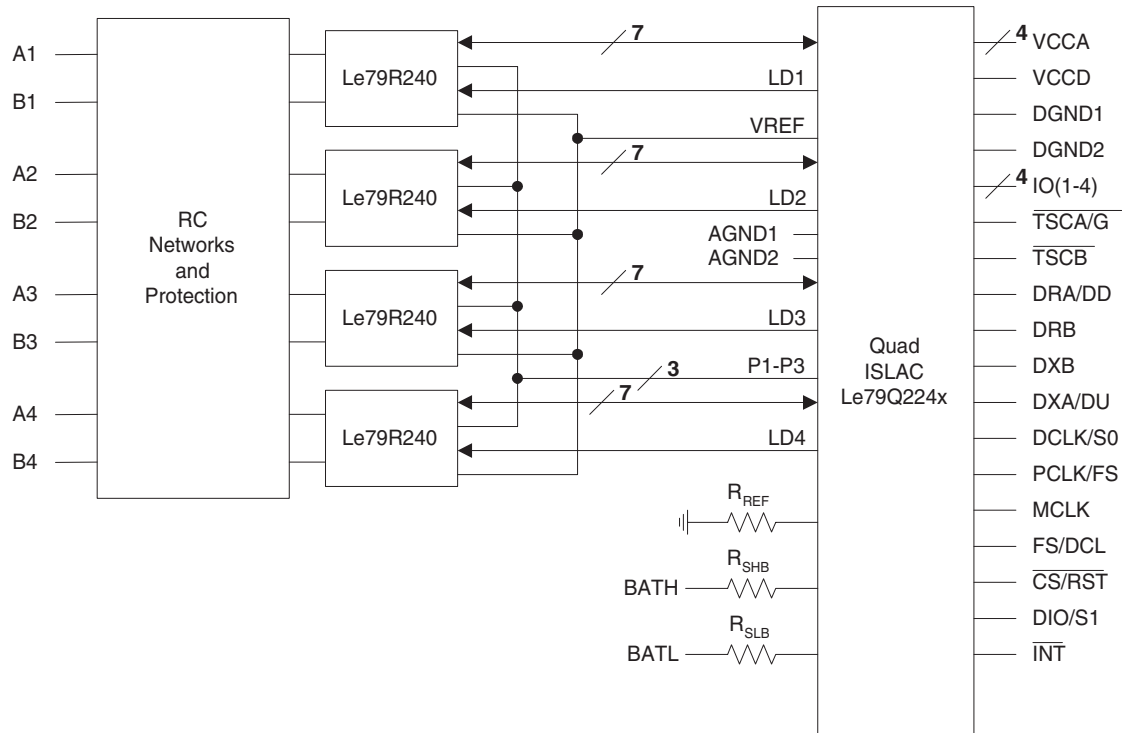
LE79R240 DEVICE INTERNAL BLOCK DIAGRAM



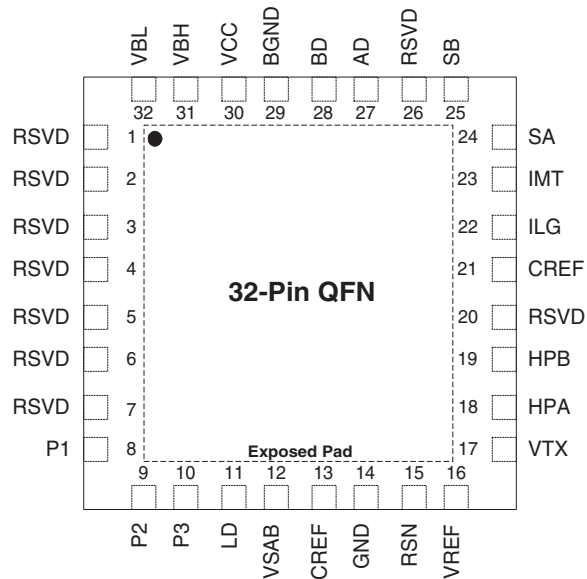
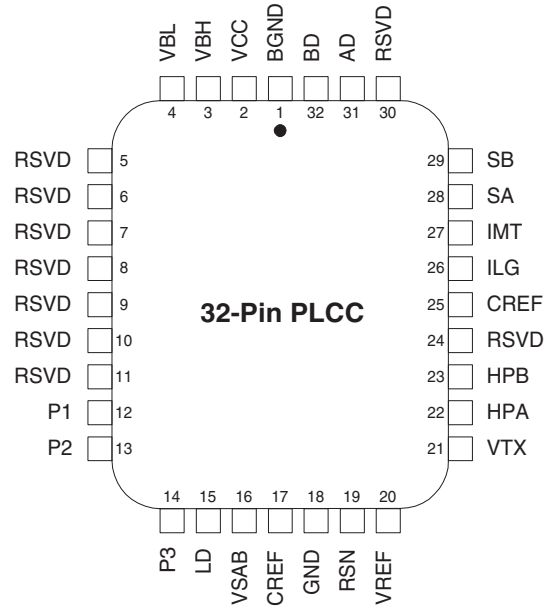
FEATURES OF THE INTELLIGENT ACCESS™ CHIP SET

- Performs all battery feed, ringing, signaling, hybrid and test (BORSCHT) functions
- Two chip solution supports high density, multi-channel architecture
- Single hardware design meets multiple country requirements through software programming of:
 - Ringing waveform and frequency
 - DC loop-feed characteristics and current-limit
 - Loop-supervision detection thresholds
 - Off-hook debounce circuit
 - Ground-key and ring-trip filters
 - Off-hook detect de-bounce interval
 - Two-wire AC impedance
 - Transhybrid balance
 - Transmit and receive gains
 - Equalization
 - Digital I/O pins
 - A-law/ μ -law and linear selection
- Supports internal balanced ringing with offset
 - Self-contained ringing generation and control
 - Integrated ring-trip filter and software enabled manual or automatic ring-trip mode
- Supports metering generation with envelope shaping
- Polarity reversal
- Supports both loop-start and ground-start signaling
- Exceeds central office requirements
- Selectable PCM or GCI interface
 - Supports most available master clock frequencies from 512 kHz to 8.192 MHz
- On-hook transmission
- Power/service denial mode
- Line-feed characteristics independent of battery voltage
- Only 5 V, 3.3 V and battery supplies needed
- Low idle-power per line
- Linear power-feed
- Compatible with inexpensive protection networks; Accommodates low-tolerance fuse resistors while maintaining longitudinal balance
- Monitors two-wire interface voltages and currents
- Power-cross, fault, and foreign voltage detection
- Integrated self-test features and built-in voice-path test modes
 - Echo gain, distortion, and noise
- Guaranteed performance over commercial temperature range.
- Small physical size

CHIP SET BLOCK DIAGRAM - FOUR CHANNEL LINE CARD EXAMPLE



CONNECTION DIAGRAM



Note:

1. Pin1 is marked for orientation.
2. RSVD = Reserved. Do not connect to this pin.
3. The thermally enhanced QFN package features an exposed pad on the underside which must be electrically tied to VBH.

PIN DESCRIPTIONS

Pin Name	Type	Description
AD, BD	Output	Provide the currents to the A and B leads of the subscriber loop.
BGND	Ground	Ground return for high and low battery supplies.
CREF	+3.3 VDC	VCCD reference. It is the digital high logic supply rail, used by the ISLIC device to ISLAC device interface.
GND	Ground	Analog and digital ground return for VCC.
HPA, HPB	Output	These pins connect to CHP, the external high-pass filter capacitor that separates the DC loop-voltage from the voice transmission path.
ILG	Output	ILG is proportional to the common-mode line current ($I_{AD} - I_{BD}$), except in disconnect mode, where ILG is proportional to the current into grounded SB.
IMT	Output	IMT is proportional to the differential line current ($I_{AD} + I_{BD}$), except in disconnect mode, where IMT is proportional to the current into grounded SA. The Le79R240 device indicates thermal overload by pulling IMT to CREF.
LD	Input	The LD pin controls the input latch and responds to a 3-level input. When the LD pin is a logic 1 ($V_{REF} + 0.3\text{ V}$), the logic levels on P1 – P3 latch into the Le79R240 device control register bits that operate the mode-decoder. When the LD pin level is at $< V_{REF} \pm 0.3\text{ V}$, the control register contents are locked.
P1 – P3	Input	Inputs to the latch for the operating-mode decoder and the relay-drivers.
RSN	Input	The metallic current between AD and BD is equal to 500 times the current into this pin. Networks that program receive gain and two-wire impedance connect to this node. This input is at a virtual potential of VREF.
RSVD	Reserved	These pins are used during Legerity testing. In the application, these pins must be left floating.
SA, SB	Input	Sense the voltages on the line side of the fuse resistors at the A and B leads. External sense resistors, RSA and RSB, protect these pins from lightning or power-cross.
VBH	Battery (Power)	Connection to high-battery supply used for ringing and long loops. Connects to the substrate. When only a single battery is available, it connects to both VBH and VBL.
VBL	Battery (Power)	Connection to low-battery supply used for short loops. When only a single battery is available, this pin can be connected to VBH.
VCC	+5 V Power Supply	Positive supply for low voltage analog and digital circuits in the Le79R240 device.
VREF	Input	The ISLAC chip provides this voltage which is used by the Le79R240 device for internal reference purposes. All analog input and output signals interfacing to the ISLAC chip are referenced to this pin.
VSAB	Output	Scaled-down version of the voltage between the sense points SA and SB on this pin.
VTX	Output	The voltage between this pin and VREF is a scaled down version of the AC component of the voltage sensed between the SA and SB pins. One end of the two-wire input impedance programming network connects to VTX. The voltage at VTX swings positive and negative with respect to VREF.
Exposed Pad	Battery	This must be electrically tied to VBH.

Absolute Maximum Ratings

Stresses greater than those listed under "Absolute Maximum Ratings" can cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods can affect device reliability.

Storage temperature	-55 to +150°C
Ambient temperature, under bias	0 to 70°C
Humidity	5% to 95%
V _{CC} with respect to GND	-0.4 to +7 V
V _{BH} , V _{BL} with respect to GND (See Note 2)	+0.4 to -95 V
BGND with respect to GND	-3 to +3 V
AD or BD to BGND: Continuous 10 ms (F = 0.1 Hz) 1 μs (F = 0.1 Hz) 250 ns (F = 0.1 Hz)	V _{BH} - 1 to BGND + 1 V _{BH} - 5 to BGND + 5 V _{BH} - 10 to BGND + 10 V _{BH} - 15 to BGND + 15
Current into SA or SB: 10 μs rise to I _{PEAK} 1000 μs fall to 0.5 I _{PEAK} 2000 μs fall to I = 0	I _{PEAK} = ±5 mA
Current into SA or SB: 2 μs rise to I _{PEAK} 10 μs fall to 0.5 I _{PEAK} 20 μs fall to I = 0	I _{PEAK} = ±12.5 mA
SA SB continuous	5 mA
Current through AD or BD	± 150 mA
P1, P2, P3, LD to GND	-0.4 to V _{CC} + 0.4 V
Maximum power dissipation, (See Note 1) T _A = 70°C In 32-pin PLCC package In 32-pin QFN package	1.67 W 3.00 W
ESD Immunity (Human Body Model)	1.5 kV min

Note:

1. Thermal limiting circuitry on chip will shut down the circuit at a junction temperature of about 165°C. Continuous operation above 145°C junction temperature may degrade device reliability.

The thermal performance of a thermally enhanced package is assured through optimized printed circuit board layout. Specified performance requires that the exposed thermal pad be soldered to an equally sized exposed copper surface, which, in turn, conducts heat through multiple vias to a large internal copper plane.

2. Rise time of V_{BH} (dv/dt) must be limited to less than 27 v/μs.

Thermal Resistance

The junction to air thermal resistance of the Le79R240 device in a 32-pin PLCC package is 45°C/W and in a 32-pin QFN package is 25 °C/W (measured under free air convection conditions and without external heat sinking).

Electrical Operating Ranges

Legerity guarantees the performance of this device over the commercial (0°C to 70°C) temperature range by conducting electrical characterization and by conducting a production test with single insertion coupled to periodic sampling. These characterization and test procedures comply with section 4.6.2 of Bellcore TR-TSY-000357 Component Reliability Assurance Requirements for Telecommunications Equipment.

Environmental Ranges

Ambient Temperature	0 to 70°C Commercial
Ambient Relative Humidity	15 to 85%

Electrical Ranges

Voltage at VCC	5 V \pm 5%
Voltage at VBL	-15 V to VBH
Voltage at VBH	-42.5 V to -90 V
BGND with respect to GND	-100 mV to +100 mV
Load resistance on VTX to VREF	20 k Ω minimum
Load resistance on VSAB to VREF	20 k Ω minimum

SPECIFICATIONS

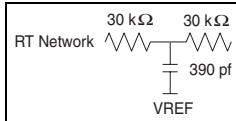
Power Dissipation

Loop resistance = 0 to ∞ unless otherwise noted (not including fuse resistors), 2 x 50 Ω fuse resistors, BATL = -24 V, BATH = -90 V, VCC = +5 V. For power dissipation measurements, DC-feed conditions are as follows:

- I_{LA} (active mode current limit) = 25 mA (I_{RSN} = 50 μ A)
- R_{FD} (feed resistance) = 500 Ω
- V_{AS} (anti-sat activate voltage) = 10 V
- V_{APP} (apparent battery voltage) = 48

Description	Test Conditions	Min	Typ	Max	Unit
Power Dissipation Normal Polarity	On-Hook Disconnect		55	80	mW
	On-Hook Standby		80	125	
	On-Hook Transmission Fixed Longitudinal Voltage	ISLIC	175	250	
	On-Hook Active High Battery	ISLIC	340	450	
	Off-Hook Active Low Battery R_L = 294 Ω	ISLIC	900	1050	
Power Supply Currents	On-Hook Disconnect	VBH	0.4	0.7	mA
		VBL	0.1		
		VCC	3.0	4.0	
	On-Hook Standby	VBH	0.75	1.2	
		VBL	0		
		VCC	3.1	4.0	
	On-Hook Transmission Fixed Longitudinal Voltage	VBH	1.85	3.0	
		VBL	0		
		VCC	5	6.5	
	On-Hook Active High Battery	VBH	3.6	5.0	
VBL		0			
VCC		7.3	8.5		
Off-Hook Active Low Battery R_L = 294 Ω	VBH	0.9	2.0		
	VBL	26.9			
	VCC	7.5	10		

DC SPECIFICATIONS



Unless otherwise specified, test conditions are: $V_{CC} = 5\text{ V}$, $BATH = -90\text{ V}$, $BATL = -24\text{ V}$, $R_{RX} = 150\text{ k}\Omega$, $R_L = 600\ \Omega$, $R_{SA} = R_{SB} = 200\text{ k}\Omega$, $R_{FA} = R_{FB} = 50\ \Omega$, $C_{HP} = 22\text{ nF}$, $C_{AD} = C_{BD} = 22\text{ nF}$, $I_{RSN} = 50\text{ mA}$, Active low battery. DC-feed conditions are normally set by the ISLAC device. When the Le79R240 device is tested by itself, its operating conditions must be simulated as if it were connected to an ideal ISLAC device.

No.	Item	Condition	Min	Typ	Max	Unit	Note
1	Two-wire loop voltage (including offset)	Standby mode, open circuit, $ V_{BH} < 55\text{ V}$ $ V_{BH} > 55\text{ V}$ $GND - VB$ Active mode, $R_L = 600\ \Omega$, $I_{RSN} = 20\ \mu\text{A}$	$V_{BH} - 8$ 48 13.5	$V_{BH} - 7$ 51 15	$V_{BH} - 6$ 55.5 56.5 16.5	V	2
2	Feed resistance per leg at pins AD & BD	Standby mode	130	250	375	W	2
3	Feed current limit	Standby mode, $R_L = 600\ \Omega$	18	34	45	mA	
	IMT current	Standby mode, $R_L = 2200\ \Omega$	44.6	56			
	ILG current	Standby mode A to VBH B to Ground	28 28			μA	
4	Ternary input voltage boundaries for LD pin. Mid-level input source must be Vref.	Low boundary High boundary Input high current Input low current Mid-level current	$C_{REF} - 1$	108 47 51	$V_{REF} + 0.3$	V V μA μA μA	2 2 2
5	Logic Inputs P1, P2, P3	Input high voltage Input low voltage Input high current Input low current	2.0 -20 -20	0 0	0.8 20 20	V V μA μA	
6	VTX output offset		-50	0	+50	mV	
7	VREF input current	$V_{REF} = 1.4\text{ V}$		50		μA	2
8	CREF input current	$C_{REF} = 3.3\text{ V}$	-3	0	3	μA	2
9	β , DC Ratio of V_{SAB} to loop voltage: $\beta = \frac{V_{SAB}}{V_{SA} - V_{SB}}$	$T_j < 145^\circ\text{C}$, $V_{SA} - V_{SB} = 22\text{ V}$	0.0088	0.0097	0.0106	V/V	
10	I_{LOOP}/I_{MT}	$I_{LOOP} = 10\text{ mA}$	275	300	325	A/A	
11	I_{LONG}/I_{LG}	$I_{LONG} = 10\text{ mA}$	560	605	650	A/A	
12	Input current, SA and SB pins	Active modes		1.0	3.0	μA	2
13	K1	Incremental DC current gain	462.5	500	537.5	A/A	2

Transmission Specifications

No.	Item	Condition	Min	Typ	Max	Unit	Note	
1	RSN input impedance	f = 300 to 3400 Hz		1		Ω	2	
2	VTX output impedance			3				
3	Max, AC + DC loop current	Active High Battery or Active Low Battery	50			mA	2	
4	Longitudinal impedance, A or B to GND	Active mode		70	135	Ω	2	
5	2-4 wire gain	-10 dBm, 1 kHz, 0 to 70°C	14.18	13.98	13.78	dB		
6	2-4 wire gain variation with frequency	300 to 3400 Hz, relative to 1 kHz	-0.15		+0.15			
7	2-4 wire gain tracking	+3 dBm to -55 dBm Reference: -10 dBm	-0.15		+0.15		5	
8	4-2 wire gain	-10 dBm, 1 kHz	-0.20		+0.20			
9	4-2 wire gain variation with frequency	300 to 3400 Hz, relative to 1 kHz	-0.1		+0.1			
10	4-2 wire gain tracking	+3 dBm to -55 dBm Reference: -10 dBm	-0.15		+0.15		5	
11	Total harmonic distortion level 2-wire	300 Hz to 3400 Hz 0 dBm			-50	dB	3	
	4-wire	-14 dBm			-48	dB	2	
	4-wire overload level at VTX OHT	R _{LOAD} = 600 Ω V _{AB} - 50 V 0 dBm		±1 -50		Vp dB	2 2	
12	Idle channel noise C-message	Active modes, R _L = 600 Ω		+9 -5	+12	dBrnC	2	
		2-wire		-8	-78	dBrnC	2	
	Psophometric Weighted	2-wire		-95		dBmp	2	
		4-wire				dBmp	2	
13	Longitudinal balance (IEEE method) Active	L - T 200 to 3400 Hz	52			dB		
		T - L 200 to 3400 Hz	40					
14	PSRR (VBH, VBL)	50 to 3400 Hz 3.4 to 50 kHz	25	45 40				3, 4 1, 2, 4
15	PSRR (VCC)	50 to 3400 Hz 3.4 to 50 kHz	25	45 35				3, 4 1, 2, 4
16	Longitudinal AC current per wire	F = 15 to 60 Hz Active mode	10				mArms	2
17	Metering distortion	Freq = 12 kHz 0.5 Vrms Freq = 16 kHz Metering load = 200 Ω	40			dB	2	

Ringling Specifications

Item	Condition	Min	Typ	Max	Unit	Note
Ringling Voltage	Active internal ringling		VBH + 6		V	7

Current-Limit Behavior

SLIC Mode	Condition	Min	Typ	Max	Unit	Note
Disconnect	Applied fault between ground and T/R		1	100	μA	6
Tip Open	Ring Short to GND	24	35	46	mA	
Standby	Short Tip to VBH Short Ring to GND	20	38	47		
		20	35	44		
Active Ringling	ISLAC device generating internal ringling		100			2

Thermal Shutdown Fault Indications

Fault	Indication
No Fault	IMT operates normally ($V_{REF} \pm 1\text{ V}$)
Thermal Shutdown	KG, IMT above 2.8 V

Note:

- These tests are performed with the following load impedances:
Frequency < 12 kHz – Longitudinal impedance = 500 Ω ; metallic impedance = 300 Ω
Frequency > 12 kHz – Longitudinal impedance = 90 Ω ; metallic impedance = 135 Ω
- Not tested or partially tested in production. This parameter is guaranteed by characterization or correlation to other tests.
- This parameter is tested at 1 kHz in production. Performance at other frequencies is guaranteed by characterization.
- When the Le79R240 device and ISLAC device is in the anti-sat operating region, this parameter is degraded. The exact degradation depends on system design.
- 55 dBm gain tracking level not tested in production. This parameter is guaranteed by characterization and correlation to other tests.
- This spec is valid from 0 V to V_{BL} or -50 V, whichever is lower in magnitude.
- Other ringing voltage characteristics are set by the ISLAC device.

Operating Modes

The Le79R240 device receives multiplexed control data on the P1, P2 and P3 pins. The LD pin then controls the loading of P1, P2, and P3 values into the proper bits in the Le79R240 device control register. When the LD pin is less than 0.3 V below V_{REF} ($V_{REF} - 0.3\text{ V}$), P1–P3 must be low. When the LD pin is more than 0.3 V above V_{REF} ($V_{REF} + 0.3\text{ V}$), P1–P3 must contain ISLIC device control data C1, C2, and C3, which are latched into the Le79R240 device control register. Connecting the LD pin to VREF locks the contents of the Le79R240 device control register.

The operating mode of the Le79R240 device is determined by the C1, C2, and C3 bits in the control register of the Le79R240 device. The following table defines the Le79R240 device operating modes set by these signals.

Table 1. Operating Modes

C3	C2	C1	Operating Mode	Battery Voltage Selection	Operating Mode
0	0	0	Standby (See Note)	High Battery (BATH) and BGND	(High ohmic feed): Loop supervision active, A and B amplifiers shut down
0	0	1	Tip Open (See Note)	High Battery (BATH) and BGND	Tip Open: AD at High-Impedance, Channel A power amplifier shut down
0	1	0	On-Hook Transmission, Fixed Longitudinal Voltage	High Battery (BATH) and BGND	Fixed longitudinal voltage of -28 V
0	1	1	Disconnect	Low Battery selection at VBL	AD and BD at High-Impedance, Channel A and B power amplifiers shut down
1	0	0	RSVD		
1	0	1	Active High Battery	High Battery (BATH) and BGND	Active feed, normal or reverse polarity
1	1	0	Active Low Battery	Low Battery (BATL) and BGND	
1	1	1	Active Internal Ringing	High Battery (BATH) and BGND	Active internal ringing

Note:

In these modes, the ring lead (B-lead) output has a -50 V internal clamp to battery ground (BGND).

Operating Mode Descriptions

Operating Mode	Description
Disconnect	This mode disconnects both A and B output amplifiers from the AD and BD outputs. The A and B amplifiers are shut down and the Le79R240 device selects the low battery voltage at the VBL pin. In the Disconnect state, the currents on IMT and ILG represent the voltages on the SA and SB pins, respectively. These currents are scaled to produce voltages across RMTi and RLGi of $\frac{V_{SA}}{400}$ and $\frac{V_{SB}}{400}$, respectively.
Standby	The power amplifiers are turned off. The AD output is driven by an internal 250 Ω (typical) resistor, which connects to ground. The BD output is driven by an internal 250 Ω (typical) resistor, which connects to the high battery (BATH) at the VBH pin, through a clamp circuit, which clamps to approximately -50 V with respect to BGND. For VBH values above -55 V, the open-circuit voltage, which appears at this output is $\sim VBH + 7$ V. If VBH is below -55 V, the voltage at this output is -50 V. The battery selection for the balance of the circuitry on the chip is VBL. Line supervision remains active. Current limiting is provided on each line to limit power dissipation under short-loop conditions as specified in "Current-Limit Behavior" on page 12. In external ringing, the standby ISLIC device state is selected.
Tip Open	In this mode, the AD (Tip) lead is opened and the BD (Ring) lead is connected to a clamp, which operates from the high battery on VBH pin and clamps to approximately -50 V with respect to BGND through a resistor of approximately 250 Ω (typical). The battery selection for the balance of the circuitry on the chip is VBL.
Active High Battery	In the Active High Battery mode, battery connections are connected as shown in Table 1. Both output amplifiers deliver the full power level determined by the programmed DC-feed conditions. Active High Battery mode is enabled during a call in applications when a long loop can be encountered.
Active Low Battery	Both output amplifiers deliver the full power level determined by the programmed DC-feed conditions. VBL, the low negative battery, is selected in the Active Low Battery mode. This is typically used during the voice part of a call.
Active Internal Ringing	In the Internal Ringing mode, the Le79R240 device selects the battery connections as shown in Table 1. When using internal ringing, both the AD and BD output amplifiers deliver the ringing signal determined by the programmed ringing level.
On-Hook Transmission (OHT), Fixed Longitudinal Voltage	In the On-Hook Transmission, Fixed Longitudinal Voltage mode, battery connections are connected as shown in Table 1. The longitudinal voltage is fixed at the voltage (also in the table above) to allow compliance with safety specifications for some classes of products.

Thermal-Management Equations

Applies to all modes except Standby, which has no thermal management.

$$I_L < 5 \text{ mA}$$

$$P_{SLIC} = (S_{BAT} - I_L(R_L + 2R_{FUSE})) \cdot I_L + 0.3 \text{ W}$$

$$P_{RTMG} = 0$$

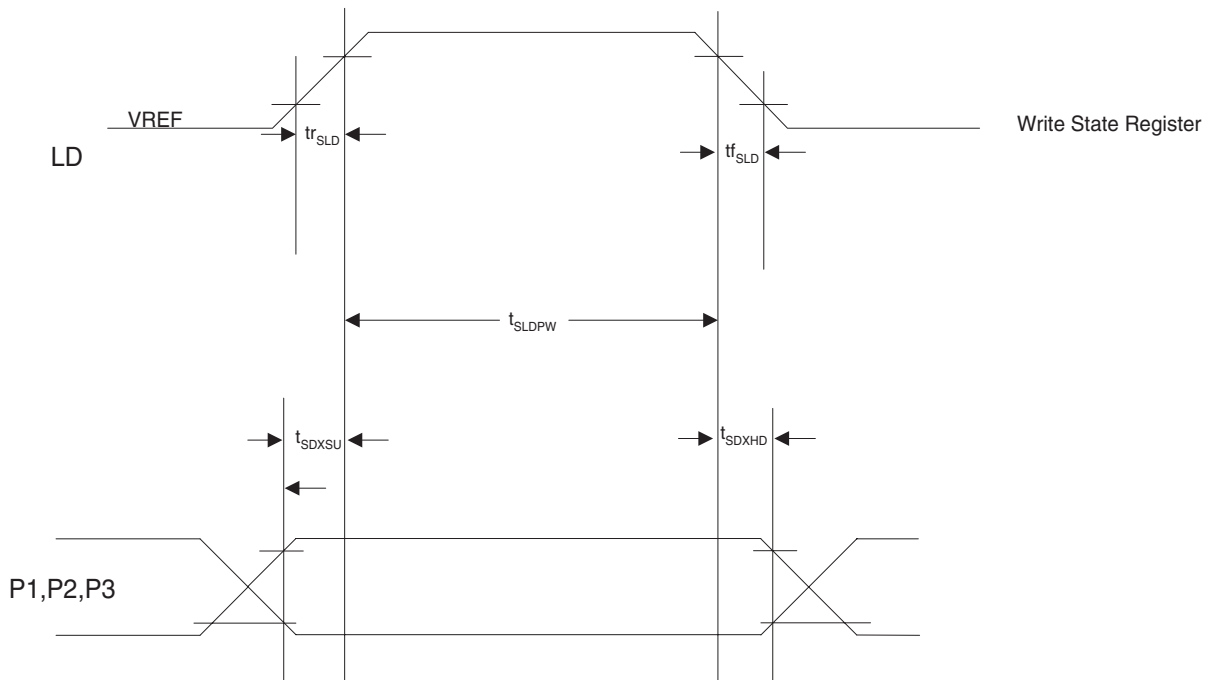
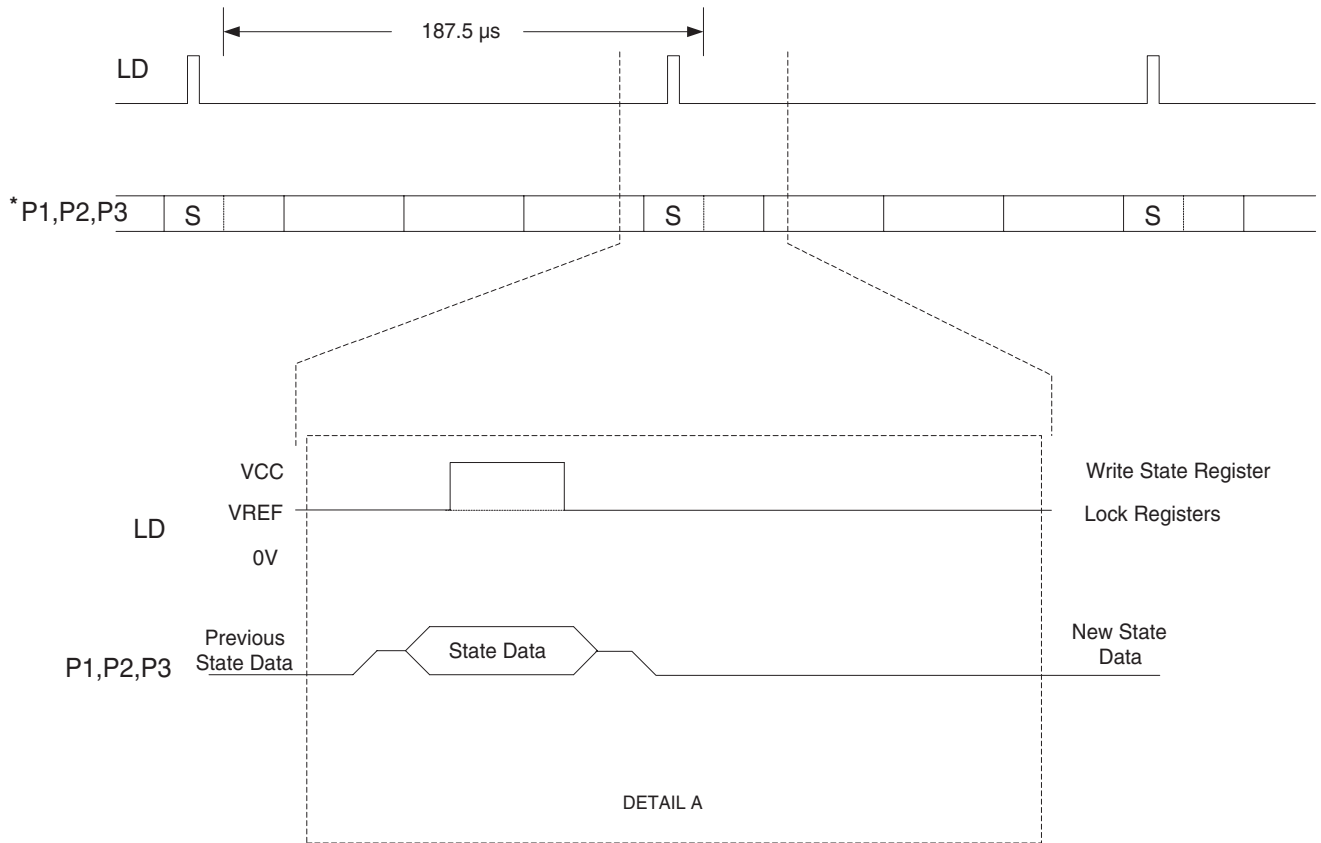
TIMING SPECIFICATIONS

Symbol	Signal	Parameter	Min	Typ	Max	Unit
t_{rSLD}	LD	Rise time Le79R240 device LD pin			2	μs
t_{fSLD}	LD	Fall time Le79R240 device LD pin			2	
t_{SLDPW}	LD	LD minimum pulse width	3			
t_{SDXSU}	P1,P2,P3	P1–P3 data Setup time	4.5			
t_{SDXHD}	P1,P2,P3	P1–P3 data hold time	4.5			

Note:

1. The P1–P3 pins are updated continuously during operation by the LD signal.
2. When writing to the ISLIC device registers, the sequence is:
 - a) Set LD pin to mid-state
 - b) Place appropriate data on the P1–P3 pins
 - c) Assert the LD pin to High to write the proper data
 - d) Return LD pin to mid-state
3. Le79R240 device registers are refreshed at 5.33 kHz when used with an ISLAC device.
4. If the clock or MPI becomes disabled, the LD pins and P1–P3 returns to 0 V state, thus protecting the Le79R240 device and the line connection.
5. Not tested in production. Guaranteed by characterization.

WAVEFORMS

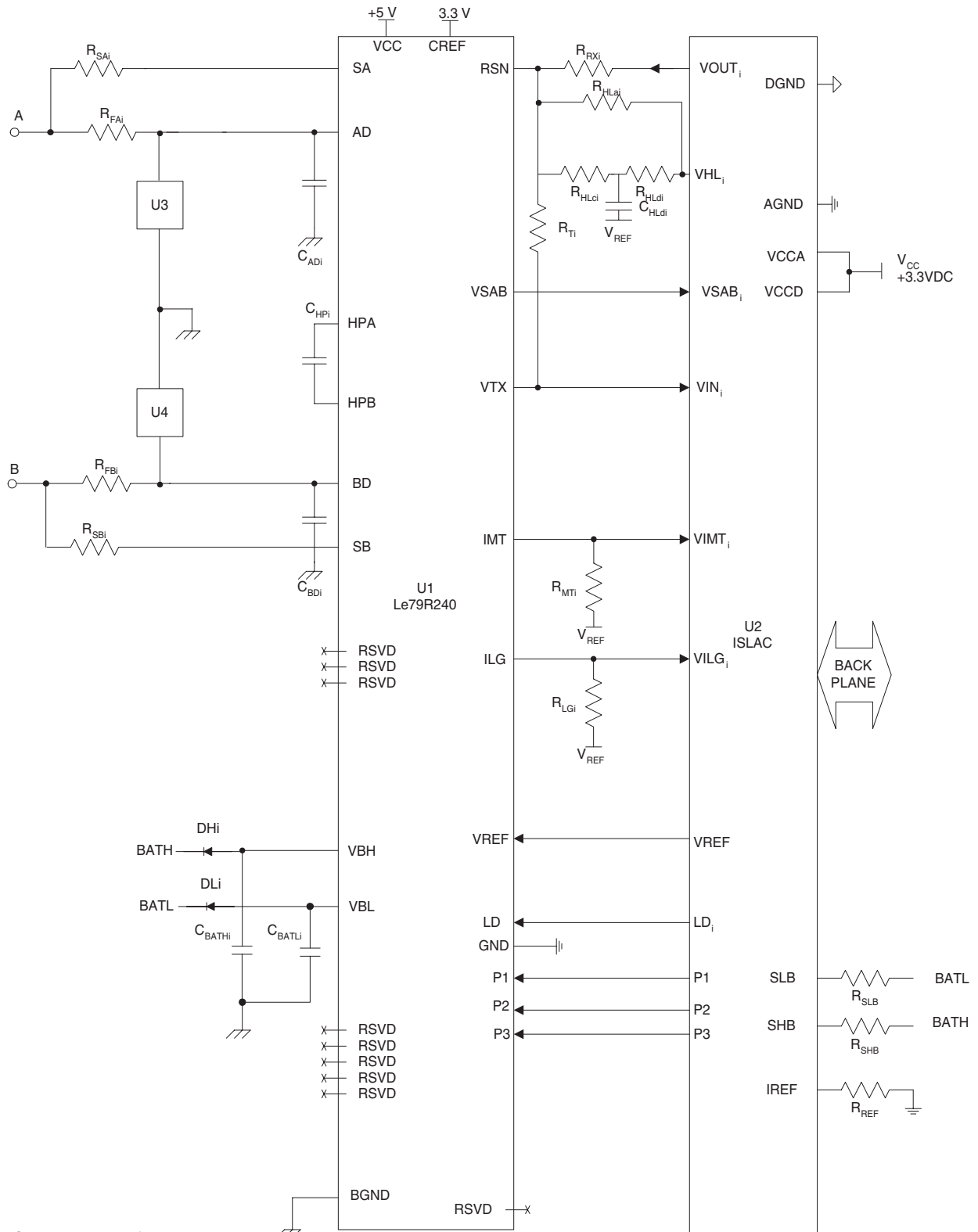


***Note:**

When the LD pin is less than 0.3 V below V_{REF} P1-P3 must be low.

APPLICATION CIRCUIT

Internal Ringing



LINE CARD PARTS LIST

The following list defines the parts and part values required to meet target specification limits for channel *i* of the line card (*i* = 1, 2).

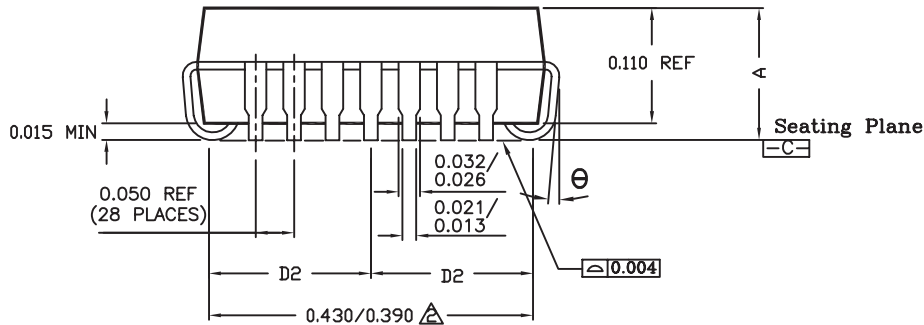
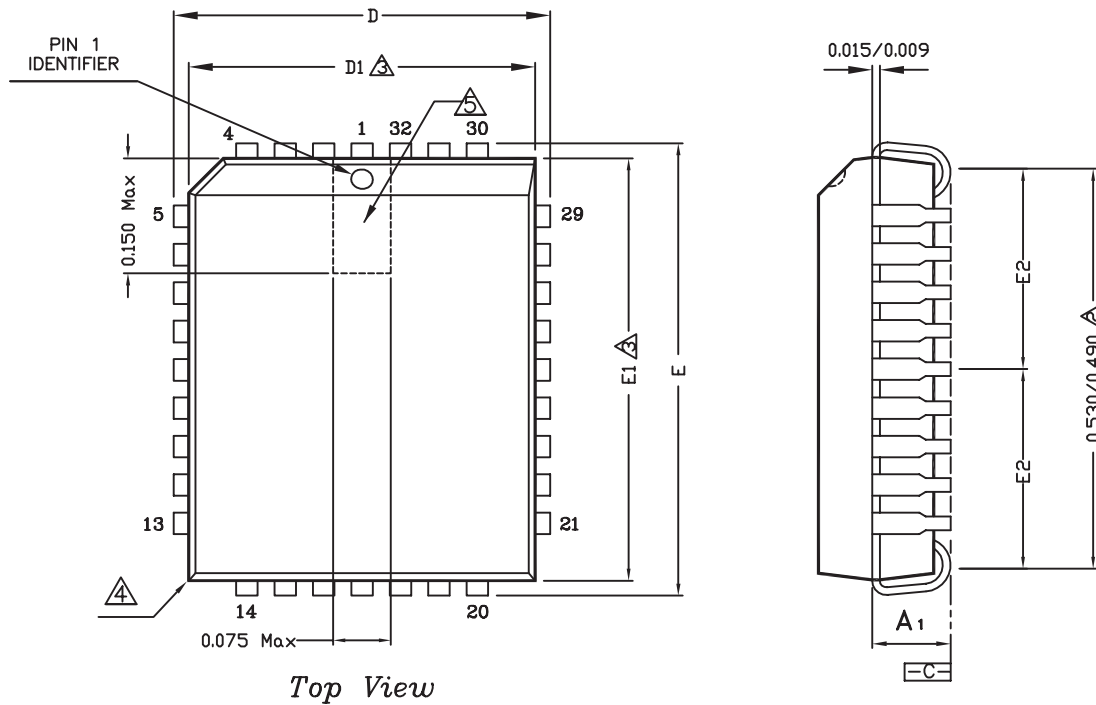
Item	Type	Value	Tol.	Rating	Comments
U1	Le79R240				ISLIC device
U2	Le79Q224x				ISLAC device
U3, U4	P0741SA				TECCOR protector
DHi, DLi	Diode	100 mA		100 V	50 ns
RFAi, RFBi	Resistor	50 Ω	5%	2 W	Fusible PTC protection resistors
RSAi, RSBi	Resistor	200 k Ω	2%	1/4 W	Sense resistors
RTi	Resistor	80.6 k Ω	1%	1/10 W	
RRXi	Resistor	100 k Ω	1%	1/10 W	
RREF	Resistor	69.8 k Ω	1%	1/10 W	Current reference
RSHB, RSLB, RSPB	Resistor	750 k Ω	1%	1/8 W	
RHLai	Resistor	40.2 k Ω	1%	1/10 W	
RHLci	Resistor	2.87 k Ω	1%	1/10 W	
RHLdi	Resistor	2.87 k Ω	1%	1/10 W	
CHLdi	Capacitor	0.82 μ F	10%	10 V	Ceramic
RMTi	Resistor	3.01 k Ω	1%	1/8 W	
RLGi	Resistor	6.04 k Ω	1%	1/8 W	
CADi, CBDi	Capacitor	22 nF	10%	100 V	Ceramic, not voltage sensitive
CBATHi, CBATLi	Capacitor	100 nF	20%	100 V	Ceramic
CHPi	Capacitor	22 nF	20%	100 V	Ceramic
CVC	Capacitor	100 nF	20%	50 V	Ceramic

Note:

1. Value can be adjusted to suit application.
2. Can be looser for relaxed ring-trip requirements.

PHYSICAL DIMENSIONS

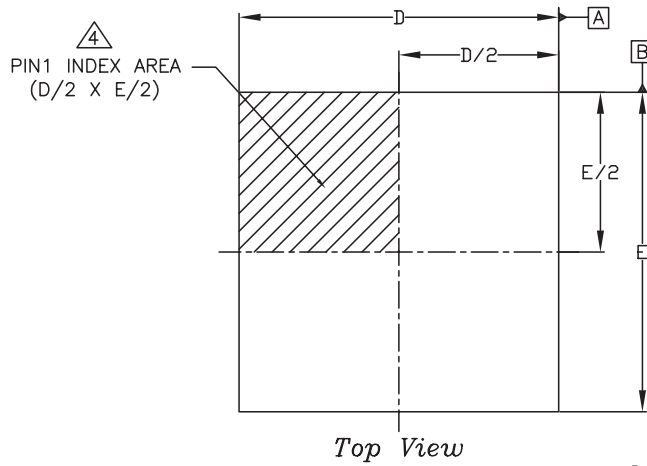
32-Pin PLCC



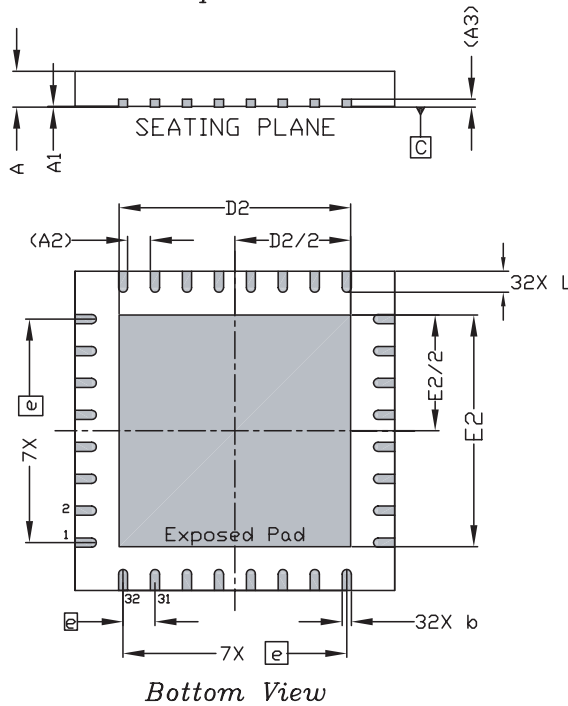
NOTE :

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- △ TO BE MEASURED AT SEATING PLANE [C] CONTACT POINT.
- △ DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTUSION. ALLOWABLE MOLD PROTUSION IS 0.010 IN PER SIDE. DIMENSIONS D, AND E, INCLUDE MOLD MISMATCH AND DETERMINED AT THE PARTING LINE; THAT IS D1 AND E1 ARE MEASURED AT THE EXTREME MATERIAL CONDITION AT THE UPPER OR LOWER PARTING LINE.
- △ EXACT SHAPE OF THIS FEATURE IS OPTIONAL.
- △ DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
6. SUM OF DAM BAR PROTUSIONS TO BE 0.007 MAX PER LEAD.
7. CONTROLLING DIMENSION : INCH.
8. REFERENCE DOCUMENT : JEDEC MS-016

Symbol	Dimension in inch		
	Min	Nom	Max
A	0.125	—	0.140
A1	0.075	0.090	0.095
D	0.485	0.490	0.495
D1	0.447	0.450	0.453
D2	0.205 REF		
E	0.585	0.590	0.595
E1	0.547	0.550	0.553
E2	0.255 REF		
θ	0°	—	10°



Symbol	Dimension in mm		
	Min	Nom	Max
A	0.80	0.90	1.00
A2	0.57 REF		
b	0.18	0.23	0.28
D	8.00 BSC		
D2	5.70	5.80	5.90
E	8.00 BSC		
E2	5.70	5.80	5.90
e	0.80 BSC		
L	0.43	0.53	0.63
N	32		
A1	0.00	0.02	0.05
A3	0.20 REF		



NOTES :

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS, θ IS IN DEGREES.
3. N IS THE TOTAL NUMBER OF TERMINALS.
4. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JEP 95-1 SSP-012. DETAILS OF THE TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
5. COPLANARITY APPLIES TO EXPOSED PAD AS WELL AS THE TERMINALS.
6. REFERENCE DOCUMENT : JEDEC MO-220

REVISION HISTORY

Revision B to C

- Applied new format.
- Added 5 REN statement and sub-bullets to “Distinctive Characteristics”
- Corrections to “Internal Ringing Application Circuit”
- Changed limits for *On-Hook Standby, Power Dissipation Normal Polarity* in “Power Dissipation” table.
- New value for VBL in “Electrical Ranges” table.
- Added V_{RING} condition to row 1 in “DC Specifications” table. Also provided min values for row 3, and created rows 15 and 16.
- Added max value for row 4 in “Transmission Specifications” table. Also changed min and max for row 6.
- Supplied ringing voltage in “Ringing Specifications” table.
- Supplied max values in “Current-Limit Behavior” table.
- Imported correct graphics for “Physical Dimensions.”

Revision C to D

- “Distinctive Characteristics changed to “Features.” 5 REN bullet changed from 9.2 to 9.55 kft and from 14.6 to 15.2 kft. Diameter information deleted from 5 REN bullet.
- “Environmental Ranges,” and “Chip Set Features” new temperature statement.
- Updated “Internal Ringing” Application Circuit for component “CBATLi” circuitry.
- “Waveforms,” new image.

Revision D to E

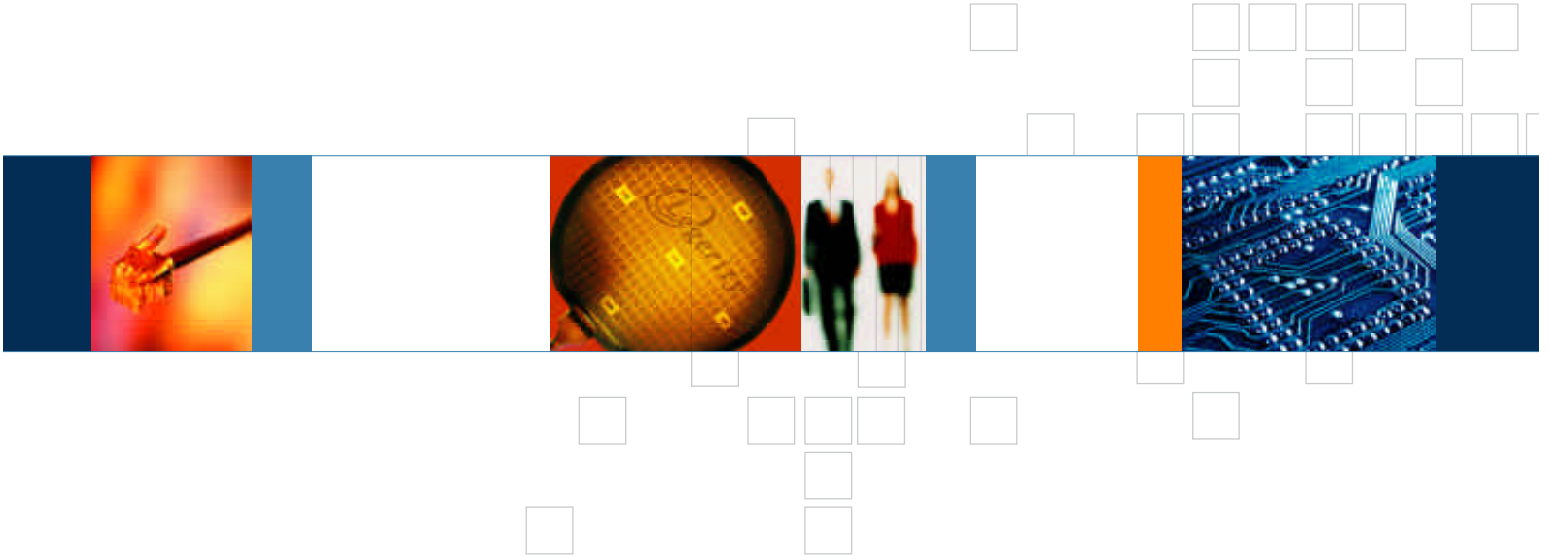
- Added QFN package data to “Connection Diagram,” “Absolute Maximum Ratings,” and “Physical Dimensions.”
- Updated “Am” OPNs (Ordering Part Numbers) to “Le” throughout document
- In “Ordering Information” the following changes were made:
 - Added entries for Le79R240JC and Le79R240QC
 - Removed the chip graphic
 - Added notes
- In “Features,” added “Foreign Voltage Sensing” feature
- Standardized notes in “Absolute Maximum Ratings” section
- Made minor edits to paragraph in “Electrical Operating Ranges” section
- Updated 32-pin PLCC physical dimensions graphic
- Removed obsolete “Sales Office Listing.”

The contents of this document are provided in connection with Legerity, Inc. products. Legerity makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice. No license, whether express, implied, arising by estoppel or otherwise, to any intellectual property rights is granted by this publication. Except as set forth in Legerity's Standard Terms and Conditions of Sale, Legerity assumes no liability whatsoever, and disclaims any express or implied warranty, relating to its products including, but not limited to, the implied warranty of merchantability, fitness for a particular purpose, or infringement of any intellectual property right. Legerity's products are not designed, intended, authorized or warranted for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or in any other application in which the failure of Legerity's product could create a situation where personal injury, death, or severe property or environmental damage may occur. Legerity reserves the right to discontinue or make changes to its products at any time without notice.

© 2002 Legerity, Inc.
All rights reserved.

Trademarks

Legerity, the Legerity logo and combinations thereof, and ISLIC, ISLAC, Intelligent Access, and WinSLAC are trademarks of Legerity, Inc. Other product names used in this publication are for identification purposes only and may be trademarks of their respective companies.



Legerity
P.O. Box 18200
Austin, Texas 78760-8200

512-228-5400 Corporate Office
512-228-5507 Fax
800-432-4009 North America Toll Free

To contact the Legerity Sales Office nearest you,
or to download or order product literature, visit
our web site at www.legerity.com

To order literature in North America,
call: 800-572-4859
or email: americalit@legerity.com

To order literature in Europe or Asia,
call: 44-0-1179-341607
or email: Europe - eurolit@legerity.com
Asia - asialit@legerity.com